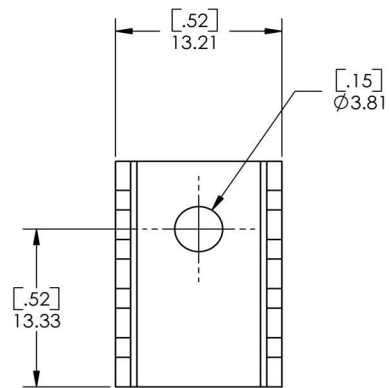
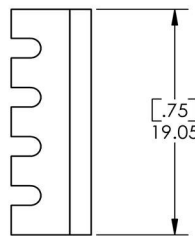
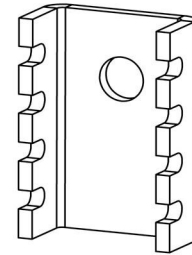
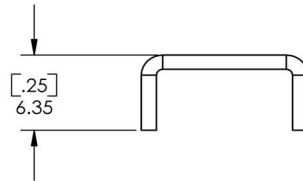
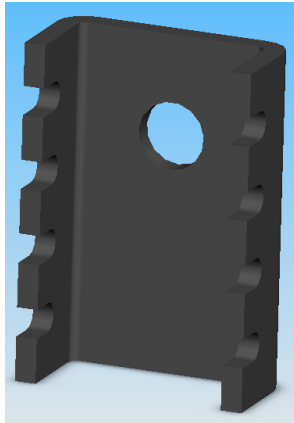


Board Level Heat Sinks



ThermaFlo

P/N: 821002B00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 6.4 x 13.2 x 19.1 mm
- Material: Aluminum, 1.2 mm Thick
- Type: Stamped
- Weight: 1.3 grams
- PCB Mounting: Solderable Device Leads
- Finish: Black Anodized
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

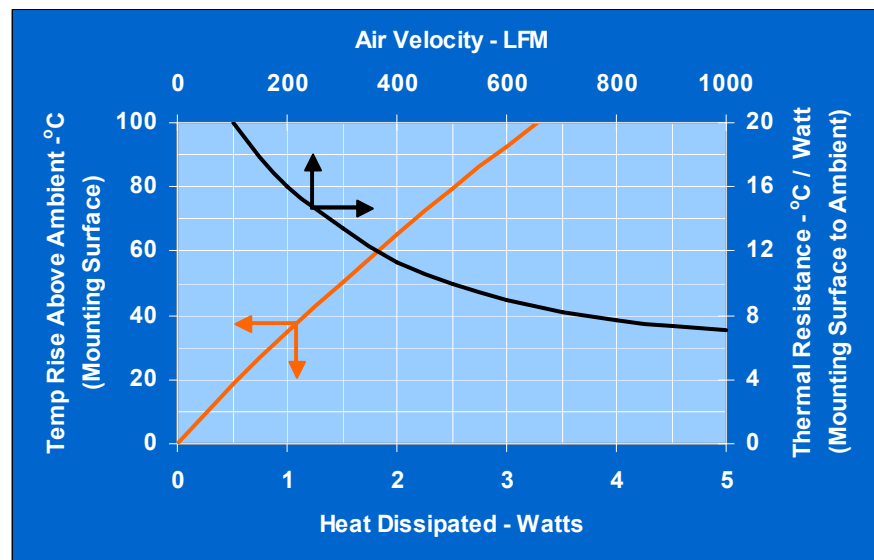
FEATURES & BENEFITS

- Hole for Device Attachment
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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